

**IN THE CLAIMS:**

1. (Currently Amended) A semiconductor bonding apparatus which bonds  
~~mounts~~ a semiconductor chip ~~via an elastic member disposed between the semiconductor chip~~  
~~and~~ to a mounting substrate, the semiconductor bonding apparatus comprising:

a holding section which holds the semiconductor chip facing the mounting  
substrate;

a translatable gas bearing which is connected to the holding section and which  
is capable of moving the semiconductor chip in a bonding direction with respect to the  
mounting substrate;

a voice coil motor connected to the translatable gas bearing;

at least one load cell which detects a pressing force ~~to be applied to the~~ for  
deforming an elastic member disposed between ~~by the holding section, when the~~  
semiconductor chip and the mounting substrate ~~is mounted~~; and

a driving section which generates a driving signal in accordance with the  
pressing force detected by the load cell to drive the voice coil motor;

wherein the driving section controls the pressing force to cause the elastic  
member to be deformable by a desired amount, whereby the semiconductor chip and the  
mounting substrate are bonded to each other, while being kept separated from each other by a  
desired distance.

2. (Original) The semiconductor bonding apparatus according to claim 1,  
further comprising:

a moving section which moves the holding section, the translatable gas bearing,  
and the voice coil motor,

wherein the load cell is disposed between the moving section and the voice coil motor.

3. (Original) The semiconductor bonding apparatus according to claim 2, wherein the load cell is further disposed on a shaft which is a bearing object of the translatory gas bearing.

4. (Original) The semiconductor bonding apparatus according to claim 3, further comprising:

a display unit which displays the pressing force detected by the two load cells.

5. (Original) The semiconductor bonding apparatus according to claim 1, further comprising:

a moving section which moves the holding section, the translatory gas bearing, and the voice coil motor,

wherein the load cell is disposed on a shaft which is a bearing object of the translatory gas bearing.

6. (Original) The semiconductor bonding apparatus according to claim 5, further comprising:

a display unit which displays the pressing force detected by the load cell.

7. (Original) The semiconductor bonding apparatus according to claim 1, further comprising:

a display unit which displays the pressing force detected by the two load cell.

8-14. (Cancelled)